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Product Change Notifications / NTDO-17SDDT634

# Product Change Notification / NTDO-17SDDT634

## **PCN Status:**

Initial notification

# PCN Type:

Manufacturing Change

#### Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MTAI as an additional assembly site for selected AT86RF215, ATmega644/1284/2564RFR2 and ATSAM4Lx8xx device families available in 48L VQFN (7x7x0.9mm) package.

#### Pre and Post Change Summary:

For AT86RF215 device family currently assembled in ASE:

ΔSEINC I		Pre Change	Post Change			
Die attach material     EN-4900F     3280       Molding compound material     G631H     G700LTD       MSL information     MSL 3     MSL 1       Lead frame material     C194     C194       DAP Surface Prep     Ag Ring plating     Bare Cu       Lead frame plating     Matte tip	Assembly Site		Microchip Technology Thailand (HQ) (MTAI)			
Molding compound material       G631H       G700LTD         MSL information       MSL 3       MSL 1         Lead frame material       C194       C194         DAP Surface Prep       Ag Ring plating       Bare Cu         Lead frame plating       Matter tip       Matter tip	Wire material	PdCu	Au			
material     G631H     G700LTD       MSL information     MSL 3     MSL 1       Lead frame material     C194     C194       DAP Surface Prep     Ag Ring plating     Bare Cu       Lead frame plating     Matter tip     Matter tip	Die attach material	EN-4900F	3280			
Lead frame material C194 C194  DAP Surface Prep Ag Ring plating Bare Cu  Lead frame plating Matter in Matter in		G631H	G700LTD			
DAP Surface Prep Ag Ring plating Bare Cu  Lead frame plating Matterin Matterin	MSL information	MSL 3	MSL 1			
Lead frame plating Matterin Matterin	Lead frame material	C194	C194			
	DAP Surface Prep	Ag Ring plating	Bare Cu			
		Matte tin	Matte tin			
No Yes		No	Yes			
Lead frame lead-lock  See Pre and Post Change attachment for lead from comparison	Lead frame lead-lock	See Pre and Post Change attachment for lead frame comparison				

Date

02-Jul-2021

**PCN Type** 

Manufacturing Change

PCN

NTDO-17SDDT634

CCB 4529 Initial Notice: Qualification of MTAI as an additional assembly site for selected AT86RF215, ATmega644/1284/2564RFR2 and ATSAM4Lx8xx device families available in 48L VQFN (7x7x0.9mm) package.

**Product Category** 

32-bit Microcontrollers, Smart Energy Wireless Communications, Wireless Modules

Affected CPNs

NTDO-

17SDDT634 Affected CPN 07022021.pdf

NTDO-

17SDDT634 Affected CPN 07022021.csv

Attachments

PCN\_NTDO-

17SDDT634 Qual Plan.pdf

PCN NTDO-17SDDT634 Pre and Post

Change Summary.pdf



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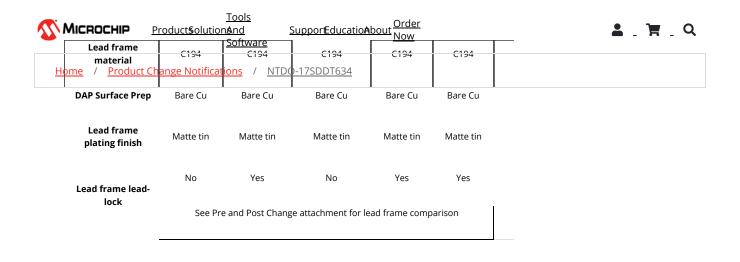
For AT86RF215, ATmega644/1284/256 ARFWATE ATSAM4Lx8xx device families currently assembled in ASE and MMT:

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	Pre	Change	Post Change				
			_				
Assembly Site	ASE Inc. (ASE)  Microchip Technology Thailand (Branch) (MMT)		ASE Inc. (ASE)	Microchip Technology Thailand (HQ) (MTAI)			
Wire material	PdCu	Au	PdCu Au		Au		
Die attach material	EN-4900F	3280	EN- 4900F	3280	3280		
Molding compound material	G631H	G700LTD	G631H	G700LTD	G700LTD		
MSL information	MSL 3	MSL 1	MSL 3	MSL 1	MSL 1		
Lead frame material	C194	C194 C194		C194	C194		
DAP Surface Prep	Ag Ring plating	Bare Cu	Ag Ring plating	Bare Cu	Bare Cu		
Lead frame plating finish	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin		
Lead frame lead-	No	Yes	No	Yes	Yes		
ЮСК	See Pre and Post Change attachment for lead frame comparison						

For ATmega2564RFR device families currently assembled in ATP7 and MMT:

· ·	Pre	e Change		Post Change				
Assembly Site	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (HQ) (MTAI)			
Wire material	AuPd	Au	AuPd	Au	Au			
Die attach material	AMK-06	3280	AMK-06	3280	3280			
Molding compound material	G700Y	G700LTD	G700Y	G700LTD	G700LTD			
MSL information	MSL 3	MSL 1	MSL 3	MSL 1	MSL 1			



## Impacts to Data Sheet:

None

## **Change Impact:**

None

#### Reason for Change:

To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

#### **Change Implementation Status:**

In Progress

## **Estimated Qualification Completion Date:**

July 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## Time Table Summary:

	July 2021				August 2021					
Workweek	27	28	29	30	31	32	33	34	35	36
Initial PCN Issue Date	X									
Qual Report Availability					Х					
Final PCN Issue Date					Х					
Estimated First Ship Date										Х

Method to Identify Change:



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**Qualification Plan:** 

<u>Software</u>

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan <u>Home</u> / <u>Product Change Notifications</u> / <u>NTDO-17SDDT634</u>

Revision History.

July 2, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local Microchip sales office with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

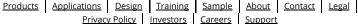












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